

NCE P-Channel Enhancement Mode Power MOSFET

Description

The NCE3415 uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as1.8V. This device is suitable for use as a load switch or in PWM applications .It is ESD protested.

General Features

● V_{DS} = -20V,I_D =-4A

 $R_{DS(ON)}$ < 36m Ω @ V_{GS} =-4.5V

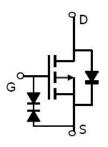
 $R_{DS(ON)}$ < 49m Ω @ V_{GS} =-2.5V

ESD Rating: 2500V HBM

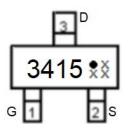
- High Power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- PWM application
- Load switch



Schematic diagram



Marking and pin Assignment



SOT-23 top view

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
3415 * ×	NCE3415	SOT-23	Ø180mm	8 mm	3000 units

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

			1
Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	Vgs	±10	V
Drain Current-Continuous	I _D	-4	А
Drain Current-Pulsed (Note 1)	I _{DM}	-30	А
Maximum Power Dissipation	P _D	1.4	W
Operating Junction and Storage Temperature Range	T_{J}, T_{STG}	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	R _{0JA}	89	°C/W

Electrical Characteristics (T_A=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						

Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =-250μA	-20	-	-	V
Zero Gate Voltage Drain Current	IDSS	V _{DS} =-20V,V _{GS} =0V	-	-	-1	μΑ
Gate-Body Leakage Current	Igss	V _{GS} =±10V,V _{DS} =0V	-	-	±10	μΑ
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =-250μA	-0.35	-0.65	-0.9	V
Drain Source On State Besistance		V _{GS} =-4.5V, I _D =-4A	-	29	36	mΩ
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =-2.5V, I _D =-4A	-	37	49	mΩ
Forward Transconductance	g FS	V _{DS} =-5V,I _D =-4A	8	-	-	S
Dynamic Characteristics (Note4)			•			
Input Capacitance	C _{lss}	\/ - 40\/\/ -0\/	-	1181.1	-	PF
Output Capacitance	Coss	V _{DS} =-10V,V _{GS} =0V,	-	121.3	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz	-	114.8	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	12		nS
Turn-on Rise Time	t _r	V _{DD} =-10V,R _L =2. 5Ω	-	10		nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =-4.5V, R_{GEN} =3 Ω	-	19		nS
Turn-Off Fall Time	t _f		-	25		nS
Total Gate Charge	Qg	\/ 40\/ L 40	-	10.2		nC
Gate-Source Charge	Q _{gs}	V _{DS} =-10V,I _D =-4A, V _{GS} =-4.5V	-	1.3	-	nC
Gate-Drain Charge	Q _{gd}		-	2.4	-	nC
Drain-Source Diode Characteristics			•			
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =-4A	-	-	-1.2	V
Diode Forward Current (Note 2)	Is		-	-	-4	Α

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- **3.** Pulse Test: Pulse Width $\leq 300 \mu s$, Duty Cycle $\leq 2\%$.
- **4.** Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

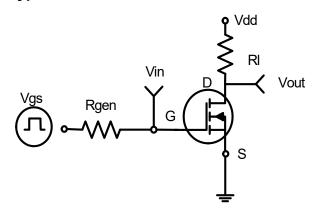


Figure 1:Switching Test Circuit

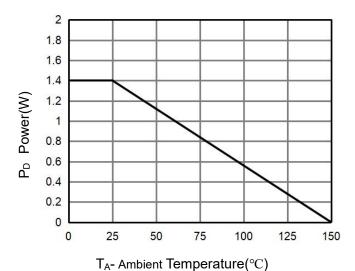


Figure 3 Power Dissipation

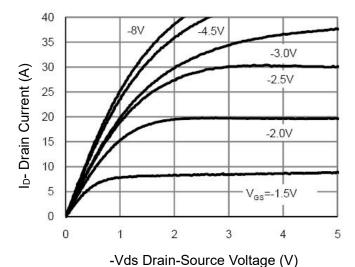


Figure 5 Output Characteristics

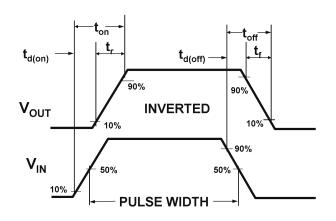


Figure 2:Switching Waveforms

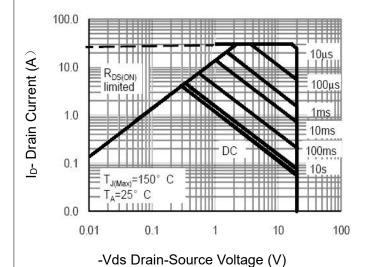


Figure 4 Safe Operation Area

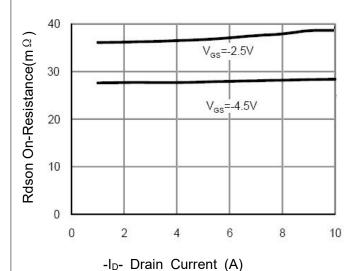


Figure 6 Drain-Source On-Resistance



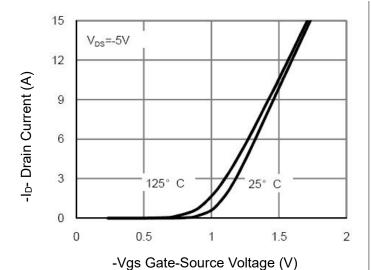
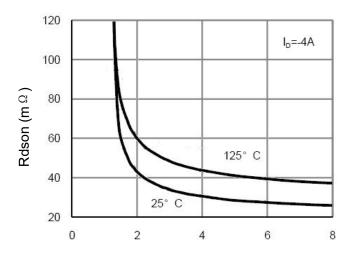


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V)
Figure 9 Rdson vs Vgs

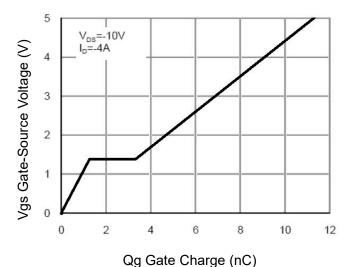


Figure 11 Gate Charge

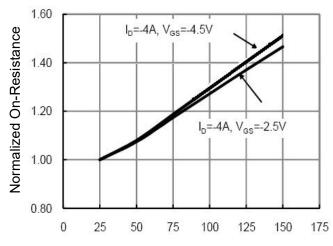
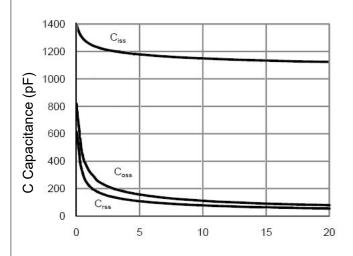


Figure 8 Drain-Source On-Resistance

T_J-Junction Temperature(°C)



Vds Drain-Source Voltage (V)
Figure 10 Capacitance vs Vds

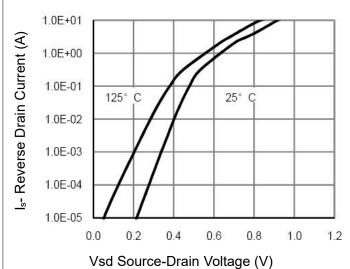
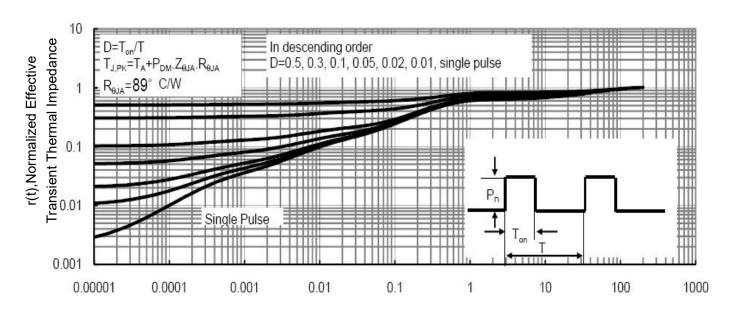


Figure 12 Source- Drain Diode Forward



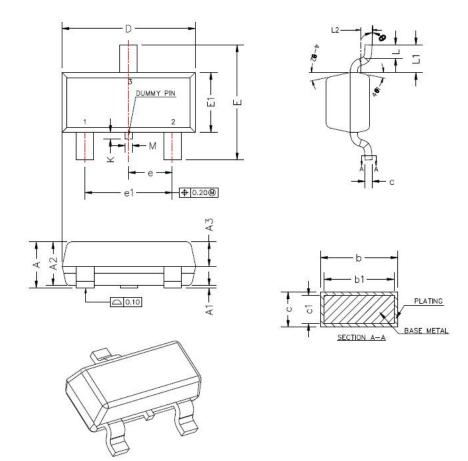


Square Wave Pluse Duration(sec)

Figure 13 Normalized Maximum Transient Thermal Impedance



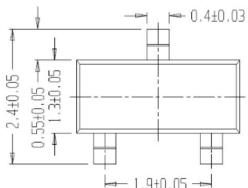
SOT-23 (E) Package Information

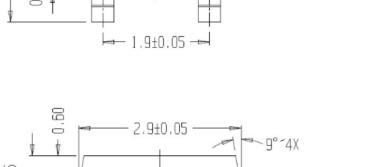


Cumbal	Millin	neters	
Symbol	Min.	Max.	
Α	0.89	1.12	
A1	0.01	0.10	
A2	0.88	1.02	
A3	0.43	0.63	
b	0.36	0.50	
b1	0.35	0.45	
С	0.14	0.20	
c1	0.14	0.16	
D	2.80	3.00	
E	2.35	2.64	
E1	1.20	1.40	
е	0.90	1.00	
e1	1.80	2.00	
L	0.40	0.60	
L1	0.6	REF	
L2		BSC	
θ	0°	8°	
01	10°	14°	
θ2	10°	14°	

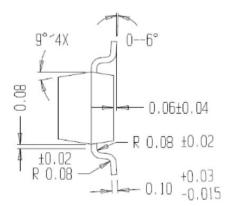


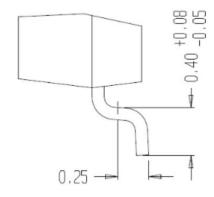
SOT-23 (R)Package Information





R 0.1 MAX







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